

L Number	Hits	Search Text	DB	Time stamp
-	90	nikoonahad-m\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/02 13:55
-	79	nikoonahad-m\$.in. and (semiconductor or wafer)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:36
-	63	nikoonahad-mehrdad\$.in.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:36
-	57	nikoonahad-mehrdad\$.in. and (semiconductor or wafer)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:38
-	38	nikoonahad-mehrdad\$.in. and scatter\$.clm.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:40
-	22	nikoonahad-mehrdad\$.in. and (scatter\$ and rotat\$).clm.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:41
-	486	scatter\$.ab. and ((semiconductor or wafer) near4 surface) and scatter\$.clm.	USPAT	2004/06/02 18:01
-	253	356/\$.ccls. and scatter\$.ab. and ((semiconductor or wafer) near4 surface) and scatter\$.clm.	USPAT	2004/06/02 13:57
-	46	356/\$.ccls. and scatter\$.ab. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT	2004/06/04 12:05
-	46	356/\$.ccls. and scatter\$.ab. and ((semiconductor or wafer) near4 surface) and rotat\$ and scatter\$.clm. and rotat\$.clm.	USPAT	2004/06/02 14:14
-	115	(356/\$ or 250/\$).ccls. and scatter\$.ab. and x\$1ray and (semiconductor or wafer)	USPAT	2004/06/02 14:16
-	31	(356/\$ or 250/\$).ccls. and scatter\$.ab. and x\$1ray and (semiconductor or wafer) and x\$1ray.clm.	USPAT	2004/06/02 17:12
-	35	(356/\$ or 250/\$).ccls. and scatter\$.ab. and (x\$1ray near6 source) and (semiconductor or wafer)	USPAT	2004/06/02 17:56
-	11	("4999014" "5042951" "5181080" "5329357" "5412473" "5596411" "5608526" "5771094" "5747813" "5917594" "6323946").pn.	USPAT	2004/06/03 16:13
-	4	("6429943" "6433878" "6483580" "6451621").pn.	USPAT	2004/06/02 18:00
-	4	scatter\$.ab. and ((semiconductor or wafer) near4 surface) and (neural adj network)	USPAT	2004/06/04 15:55
-	2	("6399944" "6316151").pn.	USPAT	2004/06/04 15:33
-	10	("4999014" "5042951" "5181080" "5329357" "5412473" "5596411" "5608526" "5771094" "5747813" "5917594" "6323946" "6429943" "6433878" "6483580" "6451621").pn. and rotat\$	USPAT	2004/06/03 16:13

-	24	("4039370"   "4141780"   "4200396"   "4303341"   "4330213"   "4408884"   "4710642"   "4905170"   "5164790"   "5241369"   "5329357"   "5381233"   "5416594"   "5607800"   "5608526"   "5739909"   "5757671"   "5835221"   "5867276"   "5923423"   "5956148"   "5963329"   "6031615"   "6118525").PN.	USPAT	2004/06/03 16:14
-	15	("4039370"   "4141780"   "4200396"   "4303341"   "4330213"   "4408884"   "4710642"   "4905170"   "5164790"   "5241369"   "5329357"   "5381233"   "5416594"   "5607800"   "5608526"   "5739909"   "5757671"   "5835221"   "5867276"   "5923423"   "5956148"   "5963329"   "6031615"   "6118525").PN.	USPAT	2004/06/03 16:15
-	12	and rotat\$ ("4039370"   "4141780"   "4200396"   "4303341"   "4330213"   "4408884"   "4710642"   "4905170"   "5164790"   "5241369"   "5329357"   "5381233"   "5416594"   "5607800"   "5608526"   "5739909"   "5757671"   "5835221"   "5867276"   "5923423"   "5956148"   "5963329"   "6031615"   "6118525").PN.	USPAT	2004/06/03 16:15
-	4	and scatter\$ and rotat\$ ("4710642"   "5164790"   "5241369"   "5703692").PN.	USPAT	2004/06/03 16:26
-	3	("4710642"   "5164790"   "5241369"   "5703692").PN. and scatter\$ and rotat\$	USPAT	2004/06/03 16:26
-	80	356/372.ior.	USPAT	2004/06/04 11:30
-	4	356/372.ior. and scatter\$.ab.	USPAT	2004/06/04 11:30
-	1514	356/\$.cor. and scatter\$.ab.	USPAT	2004/06/04 11:31
-	1299	356/\$.cor. and scatter\$.ab. and scatter\$.clm.	USPAT	2004/06/04 11:31
-	478	356/\$.cor. and scatter\$.ab. and scatter\$.clm. and @pd>19980101	USPAT	2004/06/04 11:32
-	208	356/\$.cor. and scatter\$.ab. and scatter\$.clm. and @pd>19980101 and (semiconductor or wafer)	USPAT	2004/06/04 11:38
-	13	356/340.ccls. and scatter\$.clm. and (semiconductor or wafer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 11:47
-	50	356/301.ccls. and scatter\$.clm. and (semiconductor or wafer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 11:48
-	1	("5164790").pn.	USPAT	2004/06/04 11:50
-	49	356/237.1,237.2-237.5.ccls. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT	2004/06/04 12:06
-	49	356/237.1,237.2-237.5.ccls. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:17
-	9	356/335-343.ccls. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 13:31
-	1	356/239.1-239.8.ccls. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 14:57